

LM340-N/LM78XX Series 3-Terminal Positive Regulators

Check for Samples: LM340-N, LM78xx

FEATURES

- Complete Specifications at 1A Load
- Output Voltage Tolerances of ±2% at T_j = 25°C and ±4% Over the Temperature Range (LM340A)
- Line Regulation of 0.01% of V_{OUT}/V of ΔV_{IN} at 1A Load (LM340A)
- Load Regulation of 0.3% of V_{OUT}/A (LM340A)
- Internal Thermal Overload Protection
- Internal Short-circuit Current Limit
- Output Transistor Safe Area Protection
- P⁺ Product Enhancement Tested

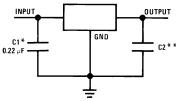
DESCRIPTION

The LM140/LM340A/LM340-N/LM78XXC monolithic 3-terminal positive voltage regulators employ internal current-limiting, thermal shutdown and safe-area compensation, making them essentially indestructible. If adequate heat sinking is provided, they can deliver over 1.0A output current. They are intended as fixed voltage regulators in a wide range of applications including local (on-card) regulation for elimination of noise and distribution problems associated with single-point regulation. In addition to use as fixed voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents.

Considerable effort was expended to make the entire series of regulators easy to use and minimize the number of external components. It is not necessary to bypass the output, although this does improve transient response. Input bypassing is needed only if the regulator is located far from the filter capacitor of the power supply.

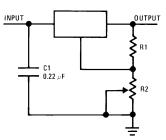
The 5V, 12V, and 15V regulator options are available in the steel TO-3 power package. The LM340A/LM340-N/LM78XXC series is available in the TO-220 plastic power package, and the LM340-N-5.0 is available in the SOT-223 package, as well as the LM340-5.0 and LM340-12 in the surface-mount DDPAK/TO-263 package.

Typical Applications



^{*}Required if the regulator is located far from the power supply filter. **Although no output capacitor is needed for stability, it does help transient response. (If needed, use 0.1 µF, ceramic disc).

Figure 1. Fixed Output Regulator



 $V_{OUT} = 5V + (5V/R1 + I_Q) R2 5V/R1 > 3 I_Q,$ load regulation (L_r) \approx [(R1 + R2)/R1] (L_r of LM340-5).

Figure 2. Adjustable Output Regulator

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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

 $I_{OUT} = \frac{V2-3}{B1} + I_{Q}$



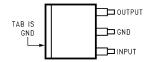


 $\Delta I_{\rm O}$ = 1.3 mA over line and load changes.

Figure 3. Current Regulator

Figure 4. Comparison between SOT-223 and DDPAK/TO-263 Packages Scale 1:1

Connection Diagrams



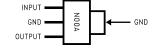


Figure 5. DDPAK/TO-263 Surface-Mount Package Top View See Package Number KTT0003B

Figure 6. 3-Lead SOT-223 Top View See Package Number DCY



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)(3)

DC Input Voltage		35V
Internal Power Dissipation ⁽⁴⁾		Internally Limited
Maximum Junction Temperature		150°C
Storage Temperature Range		−65°C to +150°C
Lead Temperature (Soldering, 10 sec.)	TO-3 Package (NDS)	300°C
	TO-220 Package (NDE), DDPAK/TO-263 Package (KTT)	230°C
ESD Susceptibility (5)		2 kV

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Conditions are conditions under which the device functions but the specifications might not be ensured. For ensured specifications and test conditions see the Electrical Characteristics
- (2) Military datasheets are available upon request. At the time of printing, the military datasheet specifications for the LM140K-5.0/883, LM140K-12/883, and LM140K-15/883 complied with the min and max limits for the respective versions of the LM140. The LM140H and LM140K may also be procured as JAN devices on slash sheet JM38510/107.
- (3) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (4) The maximum allowable power dissipation at any ambient temperature is a function of the maximum junction temperature for operation (T_{JMAX} = 125°C or 150°C), the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A). P_{DMAX} = (T_{JMAX} ¬ T_A)/θ_{JA}. If this dissipation is exceeded, the die temperature will rise above T_{JMAX} and the electrical specifications do not apply. If the die temperature rises above 150°C, the device will go into thermal shutdown. For the TO-3 package (NDS), the junction-to-ambient thermal resistance (θ_{JA}) is 39°C/W. When using a heatsink, θ_{JA} is the sum of the 4°C/W junction-to-case thermal resistance (θ_{JC}) of the TO-3 package and the case-to-ambient thermal resistance of the heatsink. For the TO-220 package (NDE), θ_{JA} is 54°C/W and θ_{JC} is 4°C/W. If SOT-223 is used, the junction-to-ambient thermal resistance is 174°C/W and can be reduced by a heatsink (see Applications Hints on heatsinking).If the DDPAK\TO-263 package is used, the thermal resistance can be reduced by increasing the PC board copper area thermally connected to the package: Using 0.5 square inches of copper area, θ_{JA} is 50°C/W; with 1 square inch of copper area, θ_{JA} is 37°C/W; and with 1.6 or more inches of copper area, θ_{JA} is 32°C/W.
- (5) ESD rating is based on the human body model, 100 pF discharged through 1.5 k Ω .

Operating Conditions⁽¹⁾

(1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Conditions are conditions under which the device functions but the specifications might not be ensured. For ensured specifications and test conditions see the Electrical Characteristics. www.ti.com

Operating Conditions⁽¹⁾ (continued)

	•	,		
			LM140	−55°C to +125°C
Temperature Range (T _A) ⁽²⁾			LM340A, LM340-N	0°C to +125°C
			LM7808C	0°C to +125°C

(2) The maximum allowable power dissipation at any ambient temperature is a function of the maximum junction temperature for operation (T_{JMAX} = 125°C or 150°C), the junction-to-ambient thermal resistance (θ_{JA}), and the ambient temperature (T_A). P_{DMAX} = (T_{JMAX} - T_A)/θ_{JA}. If this dissipation is exceeded, the die temperature will rise above T_{JMAX} and the electrical specifications do not apply. If the die temperature rises above 150°C, the device will go into thermal shutdown. For the TO-3 package (NDS), the junction-to-ambient thermal resistance (θ_{JA}) is 39°C/W. When using a heatsink, θ_{JA} is the sum of the 4°C/W junction-to-case thermal resistance (θ_{JC}) of the TO-3 package and the case-to-ambient thermal resistance of the heatsink. For the TO-220 package (NDE), θ_{JA} is 54°C/W and θ_{JC} is 4°C/W. If SOT-223 is used, the junction-to-ambient thermal resistance is 174°C/W and can be reduced by a heatsink (see Applications Hints on heatsinking). If the DDPAK\TO-263 package is used, the thermal resistance can be reduced by increasing the PC board copper area thermally connected to the package: Using 0.5 square inches of copper area, θ_{JA} is 50°C/W; with 1 square inch of copper area, θ_{JA} is 37°C/W; and with 1.6 or more inches of copper area, θ_{JA} is 32°C/W.



LM340A Electrical Characteristics

 $I_{OUT} = 1A$, $0^{\circ}C \le T_{J} \le + 125^{\circ}C$ (LM340A) unless otherwise specified⁽¹⁾

		Output Vo	Itage		5V			12V			15V		
Symbol	Input Voltag	je (unless	otherwise noted)		10V			19V			23V		Units
	Parameter	C	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Vo	Output	$T_J = 25^{\circ}C$		4.9	5	5.1	11.75	12	12.25	14.7	15	15.3	V
	Voltage	P _D ≤ 15W	, 5 mA ≤ I _O ≤ 1A	4.8		5.2	11.5		12.5	14.4		15.6	V
		$V_{MIN} \le V_{IN}$	I ≤ V _{MAX}	(7.5	$\leq V_{1N} \leq$	20)	$(14.8 \le V_{IN} \le 27)$			(17.9	9 ≤ V _{IN} :	≤ 30)	V
ΔV_{O}	Line	I _O = 500 n	nA			10			18			22	mV
	Regulation	ΔV_{IN}		(7.5	$\leq V_{IN} \leq$	20)	(14.8	3 ≤ V _{IN} ≤	27)	(17.9	9 ≤ V _{IN} :	≤ 30)	V
ı		$T_J = 25^{\circ}C$			3	10		4	18	4 22			mV
		ΔV_{IN}		(7.5	$(7.5 \le V_{IN} \le 20)$			$(14.5 \le V_{IN} \le 27)$			$(17.5 \le V_{IN} \le 30)$		
		$T_J = 25^{\circ}C$				4			9			10	mV
		Over Tem	perature			12	30					30	mV
		ΔV_{IN}		(8 ≤	≤ V _{IN} ≤ ′	12)	(16	$\leq V_{IN} \leq 1$	22)	(20	$\leq V_{IN} \leq$	26)	V
ΔV_{O}	Load	$T_J = 5 \text{ mA} \le I_O \le 1.5 \text{A}$			10	25		12	32		12	35	mV
	Regulation	25°C	250 mA ≤ I _O ≤ 750 mA			15			19			21	mV
		Over Tem	Over Temperature,			25			60			75	mV
		5 mA ≤ I _O	≤ 1A										
I_{Q}	Quiescent	$T_J = 25^{\circ}C$			6			6			6	mA	
	Current	Over Tem	perature			6.5			6.5			6.5	mA
ΔI_Q	Quiescent				0.5			0.5			0.5		mA
	Current Change	$T_J = 25^{\circ}C$, I _O = 1A			8.0			8.0			8.0	mA
		$V_{MIN} \le V_{IN}$	(7.5	$\leq V_{IN} \leq$	20)	(14.8	3 ≤ V _{IN} ≤	27)	(17.9	9 ≤ V _{IN} :	≤ 30)	V	
		$I_0 = 500 \text{ n}$	nA	0.8			0.8					8.0	mA
		$V_{MIN} \le V_{IN}$	I ≤ V _{MAX}	(8 ≤	≤ V _{IN} ≤ 2	25)	(15	$\leq V_{IN} \leq 1$	30)	(17.9	9 ≤ V _{IN} :	≤ 30)	V
V_N	Output Noise Voltage	T _A = 25°C kHz	f, 10 Hz ≤ f ≤ 100		40			75			90		μV
ΔV _{IN}	Ripple Rejection	T _J = 25°C 1A	, f = 120 Hz, I _O =	68	80		61	72		60	70		dB
ΔV _{OUT}		or f = 120	Hz, $I_O = 500$ mA,	68			61			60			dB
		Over Tem	perature,										
		$V_{MIN} \le V_{IN}$	I ≤ V _{MAX}	(8 ≤	≤ V _{IN} ≤ ′	18)	(15	$\leq V_{IN} \leq 1$	25)	(18.5	$\leq V_{IN} \leq$	28.5)	V
R _O	Dropout Voltage	$T_J = 25^{\circ}C$, I _O = 1A		2.0			2.0			2.0		V
	Output Resistance	f = 1 kHz			8			18			19		mΩ
	Short-Circuit Current	$T_J = 25^{\circ}C$			2.1			1.5			1.2		Α
	Peak Output Current	$T_J = 25^{\circ}C$			2.4			2.4			2.4		Α
	Average TC of V _O	Min, T _J =		-0.6			-1.5			-1.8		mV/°C	
V _{IN}	Input Voltage Required to Maintain Line Regulation	T _J = 25°C	T _J = 25°C				14.5			17.5			V

⁽¹⁾ All characteristics are measured with a 0.22 μF capacitor from input to ground and a 0.1 μF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.



LM140 Electrical Characteristics(1)

-55°C ≤ T_J ≤ +150°C unless otherwise specified

-	C	Output Volt	age		5V			12V			15V		
Symb	Input Voltage	e (unless of	therwise noted)		10V			19V			23V		Units
ol	Parameter		onditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	†
Vo	Output Voltage		, 5 mA ≤ I _O ≤ 1A	4.8	5	5.2	11.5	12	12.5	14.4	15	15.6	V
Ü			, 5 mA ≤ I _O ≤ 1A	4.75		5.25	11.4		12.6	14.25		15.75	V
		V _{MIN} ≤ V _{IN}	-	(8	≤ V _{IN} ≤ 2	20)	(15.	5 ≤ V _{IN} ≤	≤ 27)	(18.	5 ≤ V _{IN} :	≤ 30)	V
Δ۷ο	Line		$T_J = 25^{\circ}C$		3	50		4	120		4	150	mV
	Regulation	mA	ΔV_{IN}	(7	≤ V _{IN} ≤ 2	25)	(14.	5 ≤ V _{IN} ≤	≤ 30)	(17.	5 ≤ V _{IN} :	≤ 30)	V
			-55°C ≤ T _J ≤ +150°C			50			120			150	mV
			ΔV_{IN}	(8	≤ V _{IN} ≤ 2	20)	(15	≤ V _{IN} ≤	27)	(18.	5 ≤ V _{IN} :	≤ 30)	V
		I _O ≤ 1A	$T_J = 25^{\circ}C$	50			120					150	mV
			ΔV_{IN}	$(7.5 \le V_{IN} \le 20)$			(14.6 ≤ V _{IN} ≤ 27)			(17.	7 ≤ V _{IN} :	≤ 30)	V
			-55°C ≤ T _J ≤ +150°C	25			60			75			mV
			ΔV_{IN}	(8 ≤ V _{IN} ≤ 12)			(16 ≤ V _{IN} ≤ 22)			(20	≤ V _{IN} ≤	26)	V
ΔV_{O}	Load Regulation	T _J = 25°C	25°C 1.5A		10	50		12	120		12	150	mV
			250 mA ≤ I _P ≤ 750 mA			25			60			75	mV
		-55°C ≤ T	J ≤ +150°C,			50			120			150	mV
		5 mA ≤ I _O	≤ 1A										
I_Q	Quiescent I _O ≤ 1A		$T_J = 25^{\circ}C$			6			6			6	mA
	Current		-55°C ≤ T _J ≤ +150°C			7			7			7	mA
ΔI_Q	Quiescent	5 mA ≤ I _O	≤ 1A		0.5			0.5			0.5		mA
	Current Change	$T_J = 25^{\circ}C$				0.8			0.8			8.0	mA
		$V_{MIN} \le V_{IN}$		(8	≤ V _{IN} ≤ 2	20)	(15	≤ V _{IN} ≤	27)	(18.	$5 \le V_{IN}$:	≤ 30)	V
		I _O = 500 n +150°C	nA, −55°C ≤ T _J ≤	0.8			0.8			0.8			mA
		$V_{MIN} \le V_{IN}$		(8	$\leq V_{IN} \leq 2$	25)	(15 ≤ V _{IN} ≤ 30)			$(18.5 \le V_{IN} \le 30)$			V
V_N	Output Noise Voltage	T _A = 25°C kHz	, 10 Hz ≤ f ≤ 100		40			75			90		μV
$\frac{\Delta V_{\text{IN}}}{\Delta V_{\text{OUT}}}$	Ripple Rejection	f = 120 Hz	$I_O \le 1A$, $T_J = 25$ °C or	68	80		61	72		60	70		dB
			I _O ≤ 500 mA, -55°C ≤ T _J ≤+150°C	68			61			60			dB
		V _{MIN} ≤ V _{IN}	≤ V _{MAX}	(8	≤ V _{IN} ≤	18)	(15	≤ V _{IN} ≤	25)	(18.5	≤ V _{IN} ≤	28.5)	V
R _O	Dropout Voltage	$T_J = 25^{\circ}C$, I _O = 1A		2.0			2.0			2.0		V
	Output Resistance	f = 1 kHz			8			18			19		mΩ
	Short-Circuit Current	T _J = 25°C			2.1			1.5			1.2		А
	Peak Output Current	T _J = 25°C	T _J = 25°C		2.4		2.4			2.4			А
	Average TC of V _{OUT}	0°C ≤ T _J ≤ mA	£ +150°C, I _O = 5		-0.6			- 1.5			-1.8		mV/°C

⁽¹⁾ All characteristics are measured with a 0.22 μF capacitor from input to ground and a 0.1 μF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.



LM140 Electrical Characteristics⁽¹⁾ (continued)

-55°C ≤ T_J ≤ +150°C unless otherwise specified

	O	utput Voltage		5V			12V			15V			
Symb	Input Voltage	Input Voltage (unless otherwise noted)				19V			23V			Units	
0.	Parameter	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	1	
V _{IN}	Input Voltage Required to Maintain Line Regulation	T _J = 25°C, I _O ≤ 1A	7.5			14.6			17.7			V	

LM340-N Electrical Characteristics⁽¹⁾

 $0^{\circ}\text{C} \le \text{T}_{\text{J}} \le +125^{\circ}\text{C}$ unless otherwise specified

	Ou	tput Volta	ge		5V			12V			15V		
Symbol	Input Voltage	unless oth	nerwise noted)		10V			19V			23V		Units
	Parameter	Co	onditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Vo	Output Voltage	$T_J = 25^{\circ}C$, 5 mA ≤ I _O ≤ 1A	4.8	5	5.2	11.5	12	12.5	14.4	15	15.6	V
		P _D ≤ 15W	, 5 mA ≤ I _O ≤ 1A	4.75		5.25	11.4		12.6	14.25		15.75	V
		V _{MIN} ≤ V _{IN}	N ≤ V _{MAX}	(7.5	5 ≤ V _{IN} ≤	£ 20)	(14.	5 ≤ V _{IN} ≤	≤ 27)	(17.	5 ≤ V _{IN} :	≤ 30)	V
ΔV_{O}	Line Regulation	$I_0 = 500$	$T_J = 25^{\circ}C$		3	50		4	120		4	150	mV
		mA	ΔV_{IN}	(7	$\leq V_{IN} \leq$	25)	(14.	5 ≤ V _{IN} ≤	≤ 30)	(17.	5 ≤ V _{IN} :	≤ 30)	V
			0°C ≤ T _J ≤ +125°C			50			120			150	mV
			ΔV_{IN}	(8	$\leq V_{IN} \leq$	20)	(15	$\leq V_{IN} \leq$	27)	(18.	5 ≤ V _{IN} :	≤ 30)	V
		$I_O \le 1A$	$T_J = 25^{\circ}C$			50			120			150	mV
			ΔV_{IN}	(7.5	$5 \le V_{IN} \le$	£ 20)	(14.	6 ≤ V _{IN} ≤	≤ 27)	(17.	7 ≤ V _{IN} :	≤ 30)	V
			0°C ≤ T _J ≤ +125°C		25				60			75	mV
			ΔV_{IN}	(8	$\leq V_{IN} \leq$	12)	(16	≤ V _{IN} ≤	22)	(20	≤ V _{IN} ≤	26)	V
ΔV_{O}	Load Regulation	T _J = 25°C	5 mA ≤ I _O ≤ 1.5A		10	50		12	120		12	150	mV
			250 mA ≤ I _O ≤ 750 mA			25			60			75	mV
		5 mA ≤ I _O ≤ +125°C	≤ 1A, 0°C ≤ T _J			50			120			150	mV
IQ	Quiescent	I _O ≤ 1A	$T_J = 25^{\circ}C$			8			8			8	mA
	Current		0°C ≤ T _J ≤ +125°C	8.5		8.5			8.5			mA	
ΔI_Q	Quiescent	5 mA ≤ I _O	≤ 1A		0.5		0.5			0.5			mA
	Current Change	$T_J = 25^{\circ}C$, I _O ≤ 1A			1.0	1.0			1.0			mA
		$V_{MIN} \le V_{IN}$	N ≤ V _{MAX}	(7.5	$5 \le V_{IN} \le$	£ 20)	(14.	8 ≤ V _{IN} ≤	≤ 27)	(17.9	9 ≤ V _{IN} :	≤ 30)	V
		I _O ≤ 500 n +125°C	nA, 0°C ≤ T _J ≤			1.0			1.0			1.0	mA
		$V_{MIN} \le V_{IN}$	√ ≤ V _{MAX}	(7	$\leq V_{IN} \leq$	25)	(14.	5 ≤ V _{IN} ≤	≤ 30)	(17.	5 ≤ V _{IN} :	≤ 30)	V
V_N	Output Noise Voltage	T _A = 25°C 100 kHz	T _A = 25°C, 10 Hz ≤ f ≤		40			75			90		μV
ΔV_{IN}	Ripple Rejection		$I_{O} \le 1A, T_{J} = 25^{\circ}C$	62	80		55	72		54	70		dB
ΔV _{OUT}		f = 120 Hz	or $I_O \le 500$ mA, $0^{\circ}C \le T_J \le$ $+125^{\circ}C$	62			55			54			dB
		$V_{MIN} \le V_{IN}$	N ≤ V _{MAX}	(8	≤ V _{IN} ≤	18)	(15	≤ V _{IN} ≤	25)	(18.5	≤ V _{IN} ≤	28.5)	V

⁽¹⁾ All characteristics are measured with a 0.22 μF capacitor from input to ground and a 0.1 μF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.



LM340-N Electrical Characteristics⁽¹⁾ (continued)

 $0^{\circ}\text{C} \le \text{T}_{\text{J}} \le +125^{\circ}\text{C}$ unless otherwise specified

	Ou	tput Voltage		5V			12V			15V		
Symbol	Input Voltage (unless otherwise noted)		10V			19V			23V		Units
	Parameter	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
R _O	Dropout Voltage	$T_J = 25^{\circ}C, I_O = 1A$		2.0	•		2.0			2.0		V
	Output Resistance	f = 1 kHz		8			18			19		mΩ
	Short-Circuit Current	T _J = 25°C		2.1			1.5			1.2		Α
	Peak Output Current	T _J = 25°C		2.4			2.4			2.4		Α
	Average TC of V _{OUT}	$0^{\circ}C \le T_{J} \le +125^{\circ}C, I_{O} = 5$ mA		-0.6			- 1.5			−1.8		mV/°C
V _{IN}	Input Voltage Required to Maintain Line Regulation	$T_J = 25^{\circ}C$, $I_O \le 1A$	7.5			14.6			17.7			V

LM7808C Electrical Characteristics

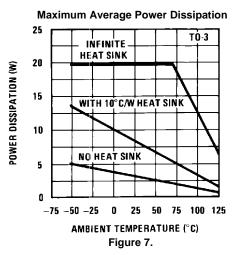
 0° C \leq T_J \leq +150°C, V_I = 14V, I_O = 500 mA, C_I = 0.33 μ F, C_O = 0.1 μ F, unless otherwise specified

Symbol	Paramete	er	Co	onditions ⁽¹⁾		LM7808C		Units
					Min	Тур	Max	
Vo	Output Voltage		$T_J = 25^{\circ}C$		7.7	8.0	8.3	V
ΔV_{O}	Line Regulation		T _J = 25°C	10.5V ≤ V _I ≤ 25V		6.0	160	mV
			11.0V ≤ V _I ≤ 17V			2.0	80	
ΔV_{O}	Load Regulation	oad Regulation		5.0 mA ≤ I _O ≤ 1.5A		12	160	mV
ĺ				250 mA ≤ I _O ≤ 750 mA		4.0	80	
Vo	Output Voltage		$11.5V \le V_1 \le 23V$, 5.0 m	7.6		8.4	V	
IQ	Quiescent Current		T _J = 25°C		4.3	8.0	mA	
ΔI_Q	Quiescent	With Line	11.5V ≤ V _I ≤ 25V				1.0	mA
	Current Change	With Load	$5.0 \text{ mA} \le I_{O} \le 1.0 \text{A}$				0.5	
V_N	Noise		$T_A = 25^{\circ}C$, 10 Hz $\leq f \leq f$	100 kHz		52		μV
$\Delta V_I/\Delta V_O$	Ripple Rejection		f = 120 Hz, I _O = 350 mA	A, T _J = 25°C	56	72		dB
V_{DO}	Dropout Voltage		I _O = 1.0A, T _J = 25°C			2.0		V
R _O	Output Resistance		f = 1.0 kHz			16		mΩ
Ios	Output Short Circuit Co	urrent	$T_J = 25^{\circ}C, V_I = 35V$			0.45		Α
I _{PK}	Peak Output Current		T _J = 25°C			2.2		Α
$\Delta V_O/\Delta T$	Average Temperature Output Voltage	Coefficient of	I _O = 5.0 mA		0.8		mV/°C	

⁽¹⁾ All characteristics are measured with a 0.22 µF capacitor from input to ground and a 0.1 µF capacitor from output to ground. All characteristics except noise voltage and ripple rejection ratio are measured using pulse techniques (t_w ≤ 10 ms, duty cycle ≤ 5%). Output voltage changes due to changes in internal temperature must be taken into account separately.



Typical Performance Characteristics



Maximum Power Dissipation (DDPAK/TO-263) (See Note 2)

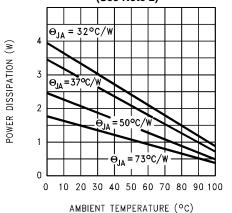
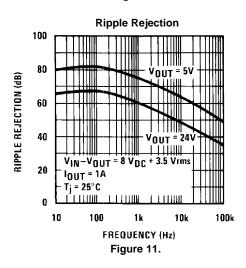
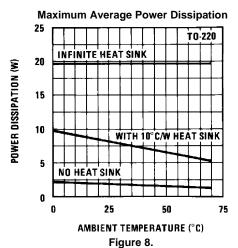
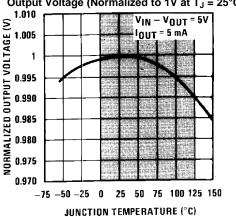


Figure 9.



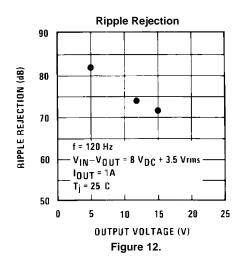


Output Voltage (Normalized to 1V at $T_J = 25$ °C)



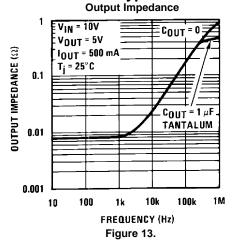
Shaded area refers to LM340A/LM340-N, LM7805C, LM7812C and LM7815C.

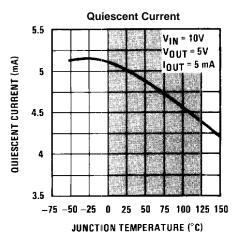
Figure 10.





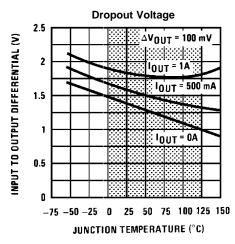
Typical Performance Characteristics (continued)





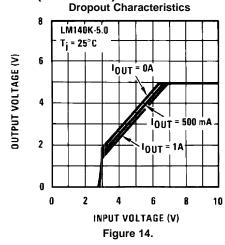
Shaded area refers to LM340A/LM340-N, LM7805C, LM7812C and LM7815C.

Figure 15.



Shaded area refers to LM340A/LM340-N, LM7805C, LM7812C and LM7815C.

Figure 17.



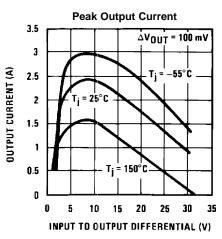


Figure 16.

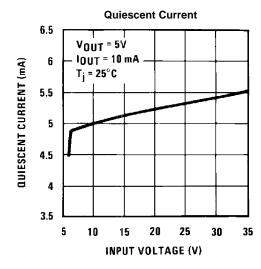
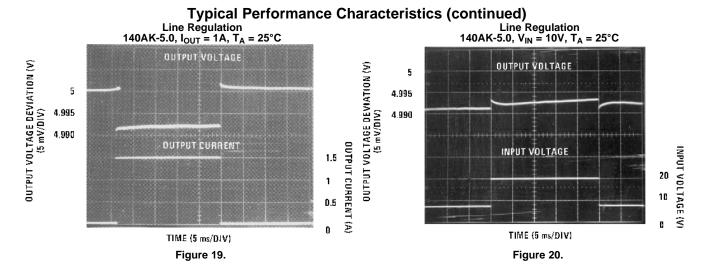
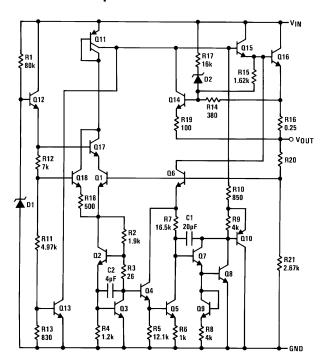


Figure 18.





Equivalent Schematic





APPLICATION HINTS

The LM340-N/LM78XX series is designed with thermal protection, output short-circuit protection and output transistor safe area protection. However, as with *any* IC regulator, it becomes necessary to take precautions to assure that the regulator is not inadvertently damaged. The following describes possible misapplications and methods to prevent damage to the regulator.

SHORTING THE REGULATOR INPUT

When using large capacitors at the output of these regulators, a protection diode connected input to output (Figure 21) may be required if the input is shorted to ground. Without the protection diode, an input short will cause the input to rapidly approach ground potential, while the output remains near the initial V_{OUT} because of the stored charge in the large output capacitor. The capacitor will then discharge through a large internal input to output diode and parasitic transistors. If the energy released by the capacitor is large enough, this diode, low current metal and the regulator will be destroyed. The fast diode in Figure 21 will shunt most of the capacitors discharge current around the regulator. Generally no protection diode is required for values of output capacitance $\leq 10 \ \mu F$.

RAISING THE OUTPUT VOLTAGE ABOVE THE INPUT VOLTAGE

Since the output of the device does not sink current, forcing the output high can cause damage to internal low current paths in a manner similar to that just described in the "Shorting the Regulator Input" section.

REGULATOR FLOATING GROUND (Figure 22)

When the ground pin alone becomes disconnected, the output approaches the unregulated input, causing possible damage to other circuits connected to V_{OUT} . If ground is reconnected with power "ON", damage may also occur to the regulator. This fault is most likely to occur when plugging in regulators or modules with on card regulators into powered up sockets. Power should be turned off first, thermal limit ceases operating, or ground should be connected first if power must be left on.

TRANSIENT VOLTAGES

If transients exceed the maximum rated input voltage of the device, or reach more than 0.8V below ground and have sufficient energy, they will damage the regulator. The solution is to use a large input capacitor, a series input breakdown diode, a choke, a transient suppressor or a combination of these.

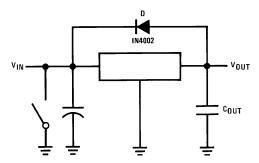


Figure 21. Input Short

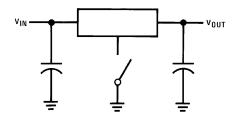


Figure 22. Regulator Floating Ground

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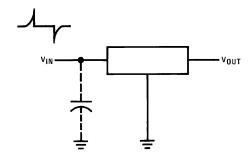


Figure 23. Transients

When a value for $\theta_{(H-A)}$ is found using the equation shown, a heatsink must be selected that has a value that is less than or equal to this number.

 $\theta_{(H-A)}$ is specified numerically by the heatsink manufacturer in this catalog, or shown in a curve that plots temperature rise vs power dissipation for the heatsink.

HEATSINKING DDPAK/TO-263 AND SOT-223 PACKAGE PARTS

Both the DDPAK/TO-263 (KTT) and SOT-223 (DCY) packages use a copper plane on the PCB and the PCB itself as a heatsink. To optimize the heat sinking ability of the plane and PCB, solder the tab of the plane.

shows for the DDPAK/TO-263 the measured values of $\theta_{(J-A)}$ for different copper area sizes using a typical PCB with 1 ounce copper and no solder mask over the copper area used for heatsinking.

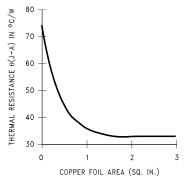


Figure 24. $\theta_{(J-A)}$ vs Copper (1 ounce) Area for the DDPAK/TO-263 Package

As shown in the figure, increasing the copper area beyond 1 square inch produces very little improvement. It should also be observed that the minimum value of $\theta_{(J-A)}$ for the DDPAK/TO-263 package mounted to a PCB is 32°C/W.

As a design aid, Figure 25 shows the maximum allowable power dissipation compared to ambient temperature for the DDPAK/TO-263 device (assuming $\theta_{(J-A)}$ is 35°C/W and the maximum junction temperature is 125°C).



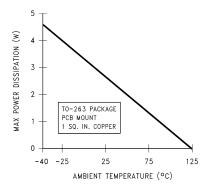


Figure 25. Maximum Power Dissipation vs T_{AMB} for the DDPAK/TO-263 Package

Figure 26 and Figure 27 show the information for the SOT-223 package. Figure 26 assumes a $\theta_{(J-A)}$ of 74°C/W for 1 ounce copper and 51°C/W for 2 ounce copper and a maximum junction temperature of 125°C.

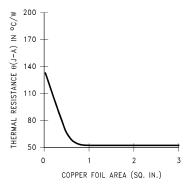


Figure 26. $\theta_{(J-A)}$ vs Copper (2 ounce) Area for the SOT-223 Package

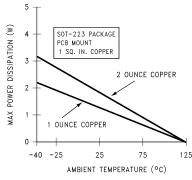
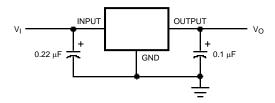


Figure 27. Maximum Power Dissipation vs T_{AMB} for the SOT-223 Package

Please see AN-1028 (SNVA036) for power enhancement techniques to be used with the SOT-223 package.

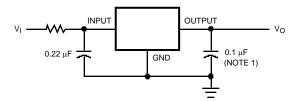


Typical Applications



Bypass capacitors are recommended for optimum stability and transient response, and should be located as close as possible to the regulator.

Figure 28. Fixed Output Regulator



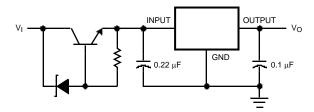
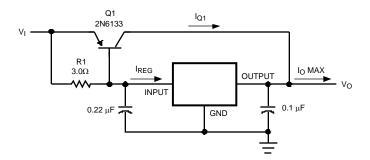


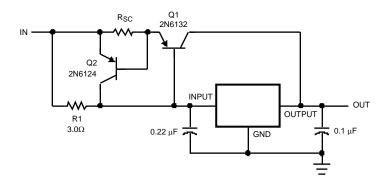
Figure 29. High Input Voltage Circuits





$$\begin{split} \beta(Q1) &\geq \frac{I_O \text{ Max}}{I_{REG \text{ Max}}} \\ R1 &= \frac{0.9}{I_{REG}} = \frac{\beta(Q1) \text{ V}_{BE(Q1)}}{I_{REG \text{ Max}}(\beta+1) - I_O \text{ Max}} \end{split}$$

Figure 30. High Current Voltage Regulator



$$R_{SC} = \frac{0.8}{I_{SC}}$$

$$R1 = \frac{\beta V_{BE(Q1)}}{I_{REG \text{ Max}} (\beta + 1) - I_{O \text{ Max}}}$$

Figure 31. High Output Current, Short Circuit Protected



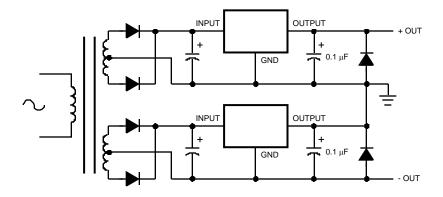


Figure 32. Positive and Negative Regulator





REVISION HISTORY

Cł	hanges from Revision H (March 2013) to Revision I	Pa	ge
•	Changed layout of National Data Sheet to TI format		16





1-Nov-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM340AT-5.0	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	0 to 70	LM340AT 5.0 P+	
LM340AT-5.0/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	0 to 70	LM340AT 5.0 P+	Samples
LM340K-5.0	ACTIVE	TO-3	NDS	2	50	TBD	Call TI	Call TI	0 to 70	LM340K -5.0 7805P+	Samples
LM340K-5.0/NOPB	ACTIVE	TO-3	NDS	2	50	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	0 to 70	LM340K -5.0 7805P+	Samples
LM340MP-5.0	NRND	SOT-223	DCY	4	1000	TBD	Call TI	Call TI	0 to 70	N00A	
LM340MP-5.0/NOPB	ACTIVE	SOT-223	DCY	4	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	N00A	Samples
LM340MPX-5.0/NOPB	ACTIVE	SOT-223	DCY	4	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	N00A	Samples
LM340S-12/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	0 to 70	LM340S -12 P+	Samples
LM340S-5.0	NRND	DDPAK/ TO-263	KTT	3	45	TBD	Call TI	Call TI	0 to 70	LM340S -5.0 P+	
LM340S-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	0 to 70	LM340S -5.0 P+	Samples
LM340SX-12	NRND	DDPAK/ TO-263	KTT	3	500	TBD	Call TI	Call TI	0 to 70	LM340S -12 P+	
LM340SX-12/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	0 to 70	LM340S -12 P+	Samples
LM340SX-5.0	NRND	DDPAK/ TO-263	KTT	3	500	TBD	Call TI	Call TI	0 to 70	LM340S -5.0 P+	
LM340SX-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	0 to 70	LM340S -5.0 P+	Samples
LM340T-12	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	0 to 70	LM340T12 7812 P+	
LM340T-12/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM340T12 7812 P+	Samples
LM340T-15	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	0 to 70	LM340T15 7815 P+	



PACKAGE OPTION ADDENDUM

1-Nov-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM340T-15/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM340T15 7815 P+	Samples
LM340T-5.0	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	0 to 70	LM340T5 7805 P+	
LM340T-5.0/LF01	ACTIVE	TO-220	NDG	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-4-260C-72 HR		LM340T5 7805 P+	Samples
LM340T-5.0/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	0 to 70	LM340T5 7805 P+	Samples
LM7812CT	NRND	TO-220	NDE	3	45	TBD	Call TI	Call TI	0 to 70	LM340T12 7812 P+	
LM7812CT/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM340T12 7812 P+	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

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TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

1-Nov-2013

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

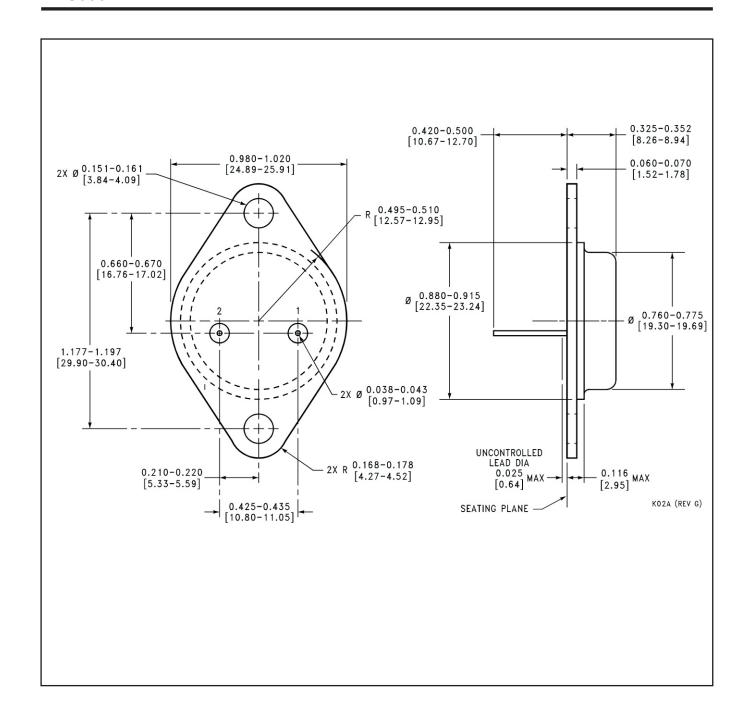
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM340MP-5.0	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM340MP-5.0/NOPB	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM340MPX-5.0/NOPB	SOT-223	DCY	4	2000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM340SX-12	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM340SX-12/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM340SX-5.0	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM340SX-5.0/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2

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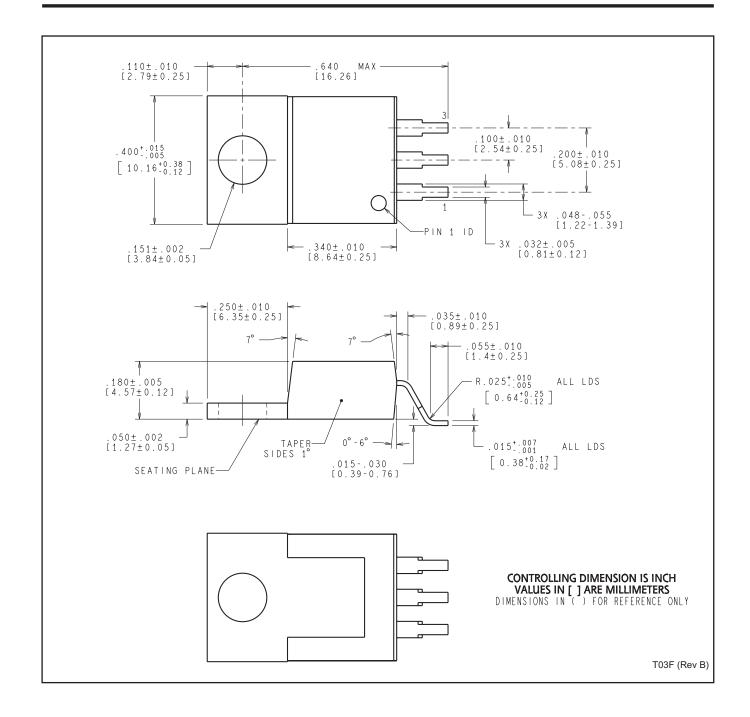


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM340MP-5.0	SOT-223	DCY	4	1000	367.0	367.0	35.0
LM340MP-5.0/NOPB	SOT-223	DCY	4	1000	367.0	367.0	35.0
LM340MPX-5.0/NOPB	SOT-223	DCY	4	2000	367.0	367.0	35.0
LM340SX-12	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM340SX-12/NOPB	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM340SX-5.0	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0
LM340SX-5.0/NOPB	DDPAK/TO-263	KTT	3	500	367.0	367.0	45.0







DCY (R-PDSO-G4)

PLASTIC SMALL-OUTLINE

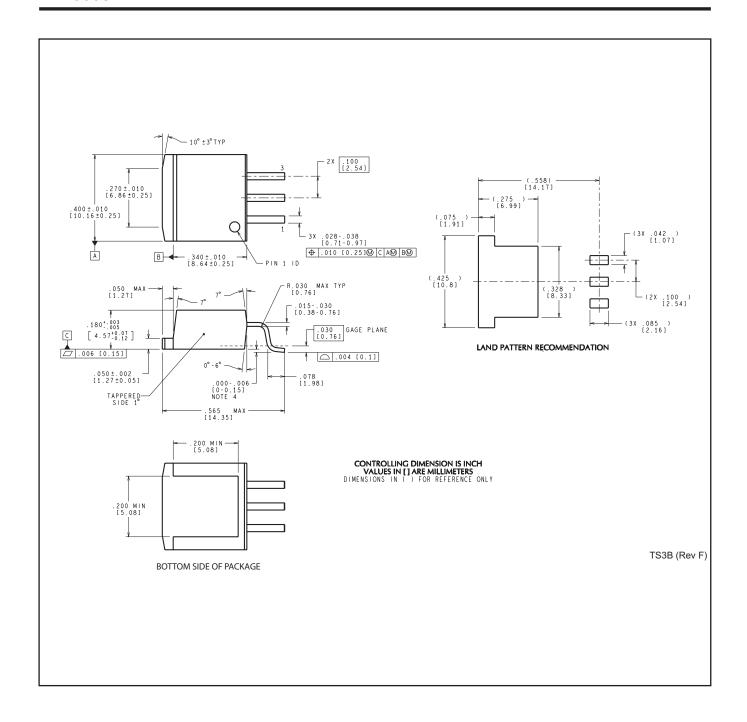


NOTES: A. All linear dimensions are in millimeters (inches).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC TO-261 Variation AA.



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